ABSTRACT

A temporary protective film for semiconductor encapsulation molding, including a support film and an adhesive layer provided on one surface or both surfaces of the support film, the temporary protective film being used for temporarily protecting a surface of a lead frame on a side opposite to a semiconductor element during encapsulation molding of forming a sealing layer that seals the semiconductor element mounted on a die pad of the lead frame. The adhesive layer contains a thermoplastic resin and a low-molecular-weight component that is a compound having a molecular weight of less than 1000. A total chlorine content in the low-molecular-weight component is 12.5% by mass or more.

Fig. 4